

2815

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PTO/SB/21 (08-00)

Approved for use through 10/31/2002. OMB 0651-0031  
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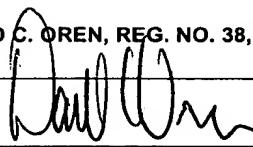
(to be used for all correspondence after initial filing)

		Application Number	09/767,830
		Filing Date	January 24, 2001
		First Named Inventor	Yamada et al.
		Group Art Unit	2815
		Examiner Name	G. Eckert II
Total Number of Pages in This Submission	<>>	Attorney Docket Number	501.39484X00

## ENCLOSURES (check all that apply)

<input type="checkbox"/> Fee Transmittal Form	<input type="checkbox"/> Assignment Papers (for an Application)	<input type="checkbox"/> After Allowance Communication to Group
<input type="checkbox"/> Fee Attached	<input type="checkbox"/> Drawing(s)	<input type="checkbox"/> Appeal Communication to Board of Appeals and Interferences
<input checked="" type="checkbox"/> Amendment / Reply	<input type="checkbox"/> Licensing-related Papers	<input type="checkbox"/> Appeal Communication to Group (Appeal Notice, Brief, Reply Brief)
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<input type="checkbox"/> Affidavits/declaration(s)	<input type="checkbox"/> Petition to Convert to a Provisional Application	<input type="checkbox"/> Status Letter
<input type="checkbox"/> Extension of Time Request	<input type="checkbox"/> Power of Attorney, Revocation Change of Correspondence Address	<input type="checkbox"/> Other Enclosure(s) (please identify below):
<input type="checkbox"/> Express Abandonment Request	<input type="checkbox"/> Terminal Disclaimer	
<input type="checkbox"/> Information Disclosure Statement	<input type="checkbox"/> Request for Refund	
<input type="checkbox"/> Certified Copy of Priority Documents	<input type="checkbox"/> CD, Number of CD(s) <<TEXT>>	
<input type="checkbox"/> Response to Missing Parts/ Incomplete Application		
<input type="checkbox"/> Response to Missing Parts under 37 CFR 1.52 or 1.53		
Remarks		

## SIGNATURE OF APPLICANT, ATTORNEY, OR AGENT

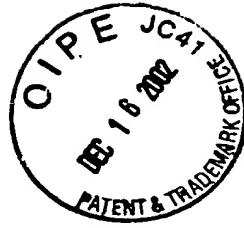
Firm or Individual Name	DAVID C. OREN, REG. NO. 38,694
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Date	DECEMBER 16, 2002

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

DEC 18 2002

Applicants: YAMADA et al. TECHNOLOGY CENTER 2600  
Serial No.: 09/767,830  
Filed: January 24, 2001  
For: SEMICONDUCTOR INTEGRATED CIRCUIT DEVICE  
AND PROCESS FOR MANUFACTURING THE SAME  
Group: 2815  
Examiner: G. Eckert II

**AMENDMENT AND RESPONSE TO RESTRICTION REQUIREMENT**

Assistant Commissioner for Patents  
Washington, D.C. 20231

December 16, 2002

Sir:

In response to the Office Action dated November 14, 2002, please  
amend the above-identified application as follows:

**IN THE SPECIFICATION:**

Please replace paragraph [0112] on page 18 of the substitute  
specification with the following rewritten paragraph:

--[0112] With respect to the dry etching technology for forming the  
isolation trenches 2a, when an etching with large anisotropy is utilized in order to  
increase the integrity of the isolation trenches 2a, the radius of curvature of the  
bottom corner within the trenches becomes small, so that stress concentrates on the  
corner parts and transposition occurs within the semiconductor substrate 1 so as to  
degrade the element isolation characteristics.--